

Transistor (PNP)

Features

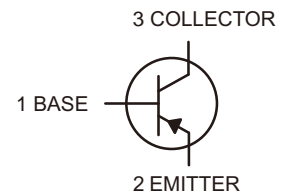
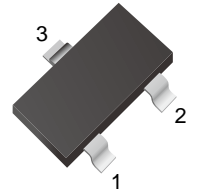
- Lead free in comply with EU RoHS 2011/65/EU directives
- High current capacity in compact package
- Epitaxial planar type

Mechanical Data

- Case:SOT-23
- Approx. Weight: 8.1mg

Ordering Information

Part Number	Marking	Shipping	Reel
LTM8550Q-TR3	LY2	3000PCS Tape&Reel	7 inches
LTM8550Q-TR12	LY2	12000PCS Tape&Reel	13 inches



Maximum Ratings (Ta=25°C)

Parameter	Symbol	Value	Unit
Collector– Base Voltage	V_{CBO}	-40	V
Collector– Emitter Voltage	V_{CEO}	-25	V
Emitter– Base Voltage	V_{EBO}	-5	V
Collector Current — Continuous	I_C	0.8	A
Collector Power Dissipation	P_C	0.3	W
Thermal Resistance From JunctionTo Ambient	R_{thJA}	417	°C/W
Operation Junction and Storage Temperature Range	T_J, T_{stg}	-55~ +150	°C

Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	$V_{(BR)CBO}$	$I_C = -0.1mA, I_E = 0$	-40			V
Collector-emitter breakdown voltage	$V_{(BR)CEO}$	$I_C = -1mA, I_B = 0$	-25			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	$I_E = -0.1mA, I_C = 0$	-5			V
Collector cut-off current	I_{CBO}	$V_{CB} = -35V, I_E = 0$			-150	nA
Collector cut-off current	I_{CEO}	$V_{CE} = -20V, I_B = 0$			-10	uA
Emitter cut-off current	I_{EBO}	$V_{EB} = -4V, I_C = 0$			-150	nA
DC current gain	h_{FE}	$V_{CE} = -1V, I_C = -100mA$	150		300	
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -800mA, I_B = -80mA$			-0.5	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C = -800mA, I_B = -80mA$			-1.2	V



Characteristics Curve

Fig.1 IC vs VCE

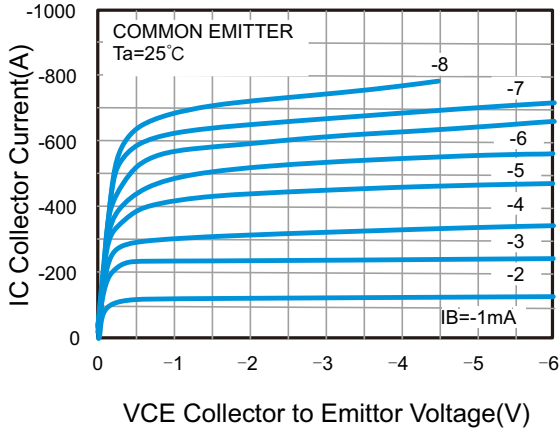


Fig.2 HFE vs IC

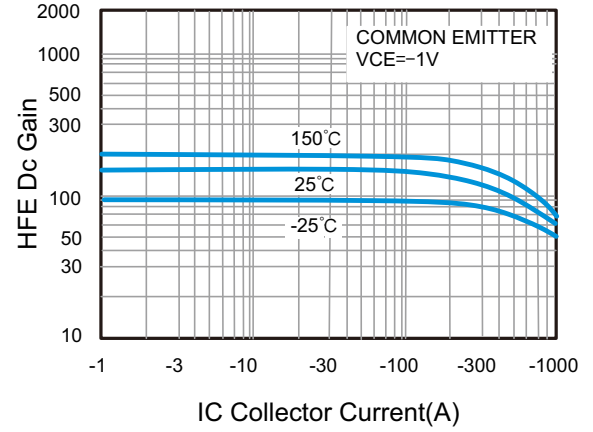


Fig.3 VCE(sat) Vs IC

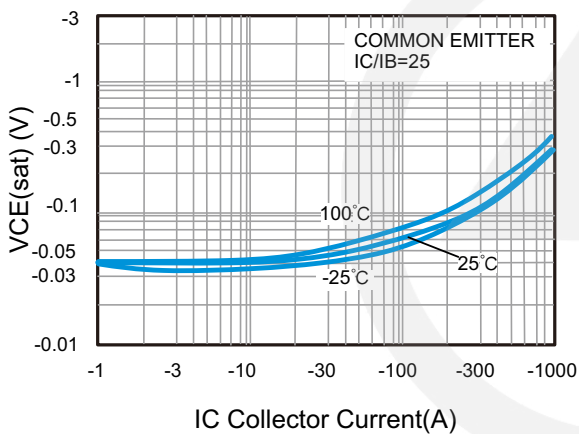
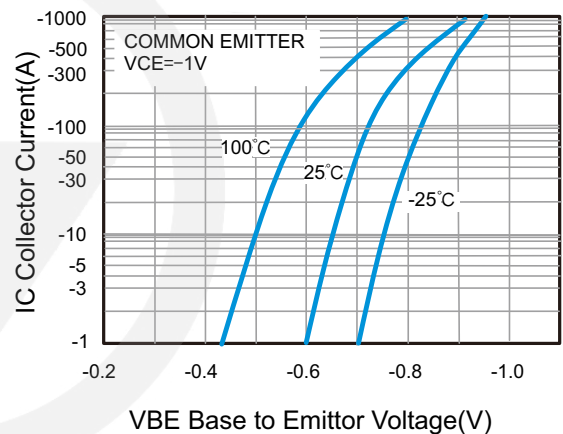


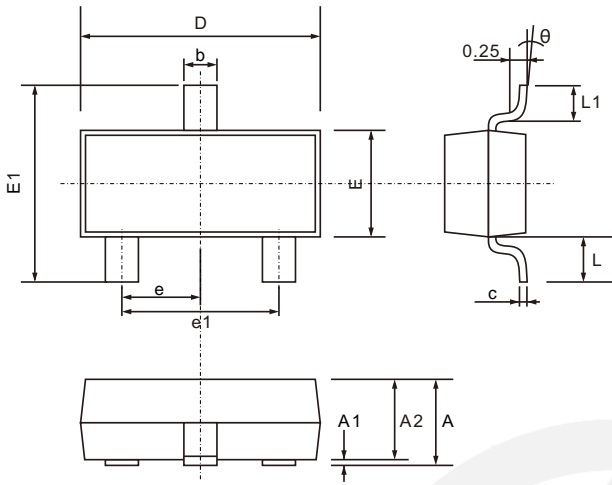
Fig.4 IC vs VBE





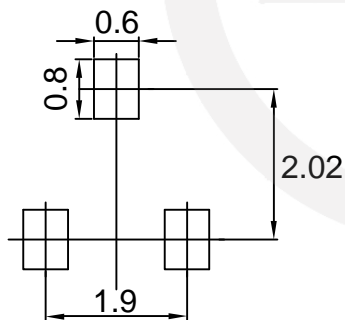
SOT-23 Package Outline

Unit: mm



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.900	1.200
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.200
D	2.700	3.100
E	1.200	1.400
E1	2.200	2.600
e	0.950 TYP.	
e1	1.750	2.050
L	0.550 TYP.	
L1	0.300	0.500
θ	0°	8°

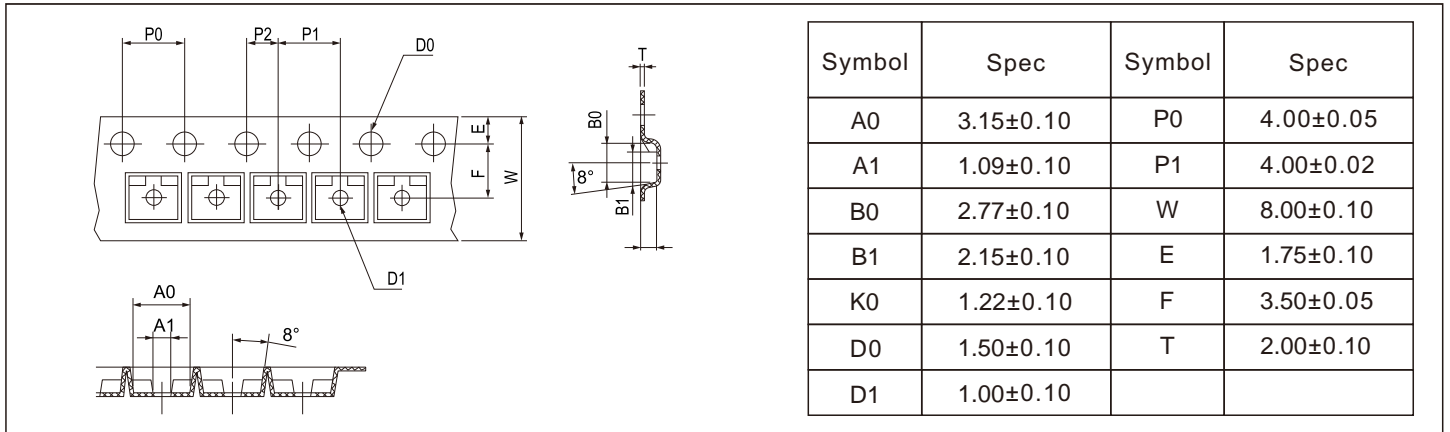
SOT-23 Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$
 3. The pad layout is for reference purpose only.

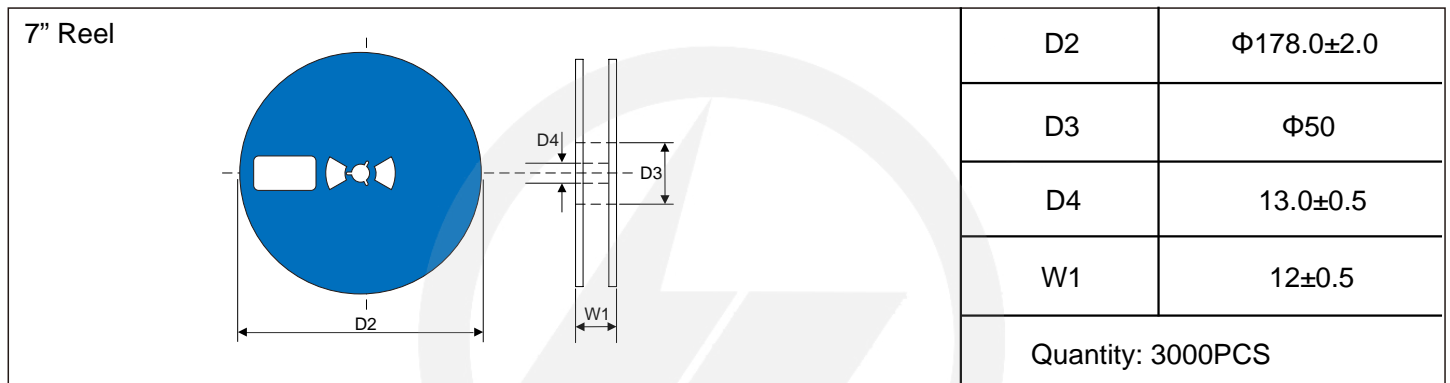
Carrier Tape Dimensions

Unit : mm



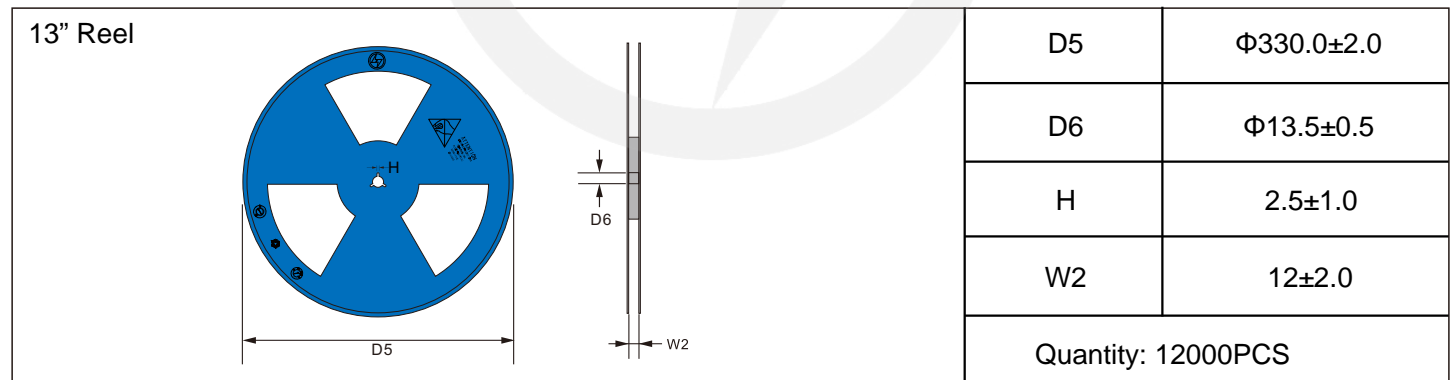
Reel Dimensions

Unit : mm

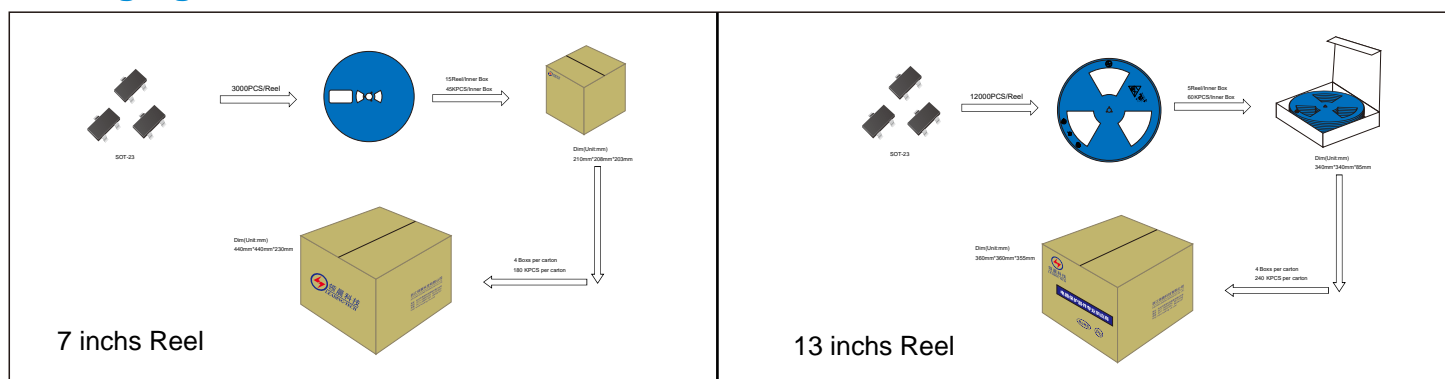


Reel Dimensions

Unit : mm



Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _s)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision Content	Revision Reason	Revision Person	Note
01	2024.03.01	2024.03.01	3.0	New file	/	Ding	
02	2025.08.27	2025.08.27	3.1	Update packaging information	/	Ding	
03	2026.03.06	2026.03.06	3.2	Package outline E1(max)=2.6mm	/	Ding	